



#### 45V N-CHANNEL ENHANCEMENT MODE MOSFET

## **Product Summary**

| V <sub>(BR)DSS</sub> | R <sub>DS(on) max</sub>       | I <sub>D</sub><br>T <sub>A</sub> = 25°C |
|----------------------|-------------------------------|---|
| 45V                  | 46mΩ @ V <sub>GS</sub> = 10V  | 4.8A                                    |
|                      | 62mΩ @ V <sub>GS</sub> = 4.5V | 4.1A                                    |

#### **Features and Benefits**

- Low Input Capacitance
- Low On-Resistance
- Fast Switching Speed
- Lead, Halogen, and Antimony Free, RoHS Compliant (Note 1)
- "Green" Device (Note 2)
- Qualified to AEC-Q101 Standards for High Reliability

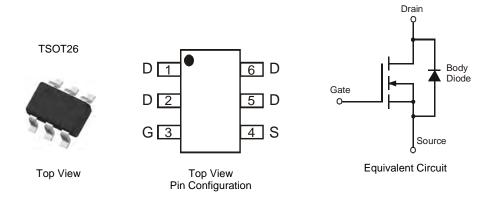
## **Description and Applications**

This new generation MOSFET has been designed to minimize the onstate resistance (R<sub>DS(on)</sub>) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- **DC-DC Converters**
- Power management functions
- Backlighting

### **Mechanical Data**

- Case: TSOT26
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Tin Finish annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.013 grams (approximate)



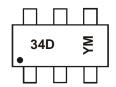
### **Ordering Information (Note 3)**

| Part Number  | Case   | Packaging         |
|--------------|--------|-------------------|
| DMN4060SVT-7 | TSOT26 | 3,000/Tape & Reel |

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. No purposely added lead. Halogen and Antimony free.
- 2. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com.
- 3. For packaging details, go to our website at http://www.diodes.com.

## **Marking Information**



34D = Product Type Marking Code YM = Date Code Marking Y = Year (ex: Z = 2012)M = Month (ex: 9 = September)

Date Code Kev

| Year  | 201 | 1   | 2012 |     | 2013 | 20  | 14  | 2015 |     | 2016 |     | 2017 |
|-------|-----|-----|------|-----|------|-----|-----|------|-----|------|-----|------|
| Code  | Υ   |     | Z    |     | Α    | -   | 3   | С    |     | D    |     | E    |
| Month | Jan | Feb | Mar  | Apr | May  | Jun | Jul | Aug  | Sep | Oct  | Nov | Dec  |
| Code  | 1   | 2   | 3    | 4   | 5    | 6   | 7   | 8    | 9   | 0    | N   | D    |

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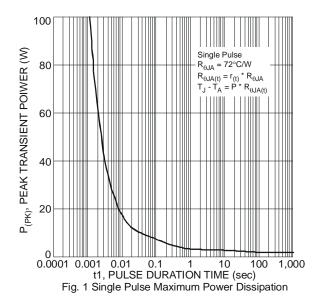


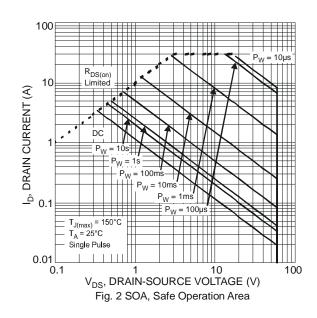
## Maximum Ratings @T<sub>A</sub> = 25°C unless otherwise specified

| Characteristic  | Symbol          | Value                          | Units          |            |   |
|---|-----------------|--------------------------------|----------------|------------|---|
| Drain-Source Voltage                                    | $V_{DSS}$       | 45                             | V              |            |   |
| Gate-Source Voltage                                     | $V_{GSS}$       | ±20                            | V              |            |   |
| Continuous Preis Correct (Note 5) V                     | Steady<br>State | $T_A = 25$ °C<br>$T_A = 70$ °C | I <sub>D</sub> | 4.8<br>3.8 | Α |
| Continuous Drain Current (Note 5) V <sub>GS</sub> = 10V | t<10s           | $T_A = 25$ °C<br>$T_A = 70$ °C | I <sub>D</sub> | 6.1<br>4.8 | Α |
| Continuous Drain Current (Note E) V                     | Steady<br>State | $T_A = 25$ °C<br>$T_A = 70$ °C | I <sub>D</sub> | 4.1<br>3.2 | А |
| Continuous Drain Current (Note 5) V <sub>GS</sub> = 5V  | t<10s           | $T_A = 25$ °C<br>$T_A = 70$ °C | I <sub>D</sub> | 5.2<br>4.1 | А |
| Maximum Body Diode Forward Current (Note 5)             | I <sub>S</sub>  | 2.1                            | Α              |            |   |
| Pulsed Drain Current (10µs pulse, duty cycle = 1%)      | I <sub>DM</sub> | 30                             | Α              |            |   |
| Avalanche Current (Note 6) L = 0.1mH                    | I <sub>AR</sub> | 14.2                           | Α              |            |   |
| Avalanche Energy (Note 6) L = 0.1mH                     | E <sub>AR</sub> | 10                             | mJ             |            |   |

# Thermal Characteristics @T<sub>A</sub> = 25°C unless otherwise specified

| Characteristic                                   |                       | Symbol                           | Value       | Units |
|--|-----------------------|----------------------------------|-------------|-------|
| Total Dawer Dissination (Note 4)                 | $T_A = 25^{\circ}C$   | р                                | 1.2         | W     |
| Total Power Dissipation (Note 4)                 | T <sub>A</sub> = 70°C | $P_{D}$                          | 0.75        | VV    |
| Thermal Resistance, Junction to Ambient (Note 4) | Steady state          | D.                               | 106         | °C/W  |
| Thermal Resistance, Junction to Ambient (Note 4) | t<10s                 | $R_{\theta JA}$                  | 69          | °C/W  |
| Total Power Dissipation (Note 5)                 | $T_A = 25^{\circ}C$   | PD                               | 1.8         | W     |
| Total Power Dissipation (Note 5)                 | T <sub>A</sub> = 70°C | PD                               | 1.1         |       |
| Thermal Resistance, Junction to Ambient (Note 5) | Steady state          | D.                               | 68          | °C/W  |
| Thermal Resistance, Junction to Ambient (Note 5) | t<10s                 | $R_{\theta JA}$                  | 44          | °C/W  |
| Thermal Resistance, Junction to Case (Note 5)    |                       | $R_{	heta JC}$                   | 20          | °C/W  |
| Operating and Storage Temperature Range          |                       | T <sub>J,</sub> T <sub>STG</sub> | -55 to +150 | °C    |





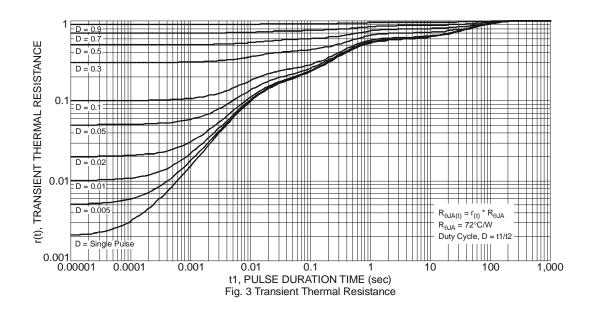


## Electrical Characteristics @T<sub>A</sub> = 25°C unless otherwise specified

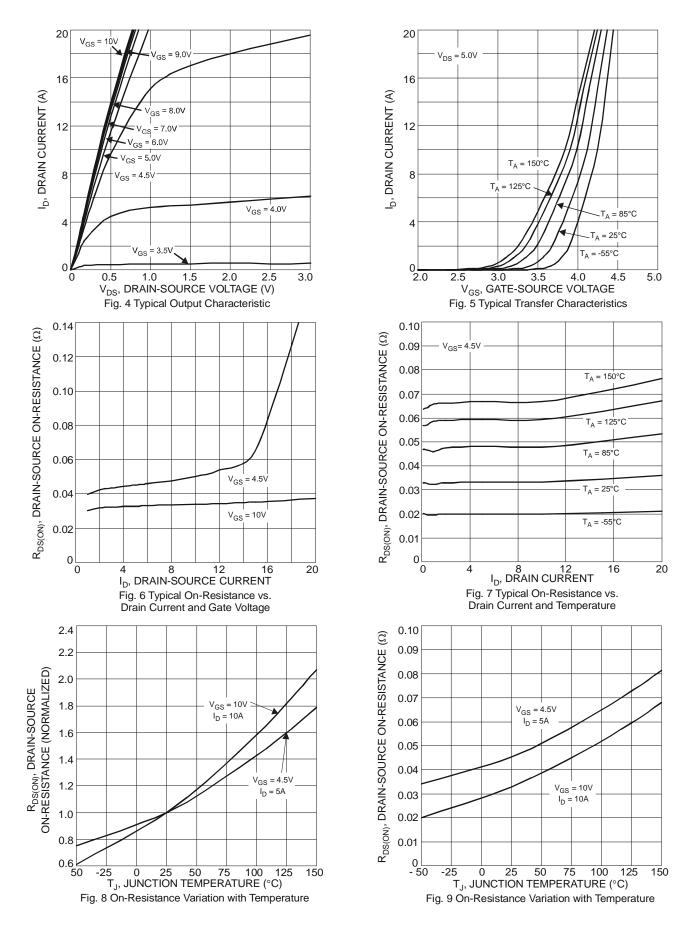
| Characteristic                             | Symbol               | Min | Тур  | Max  | Unit       | Test Condition                               |
|--|----------------------|-----|------|------|------------|--|
| OFF CHARACTERISTICS (Note 7)               |                      |     |      |      |            |  |
| Drain-Source Breakdown Voltage             | BV <sub>DSS</sub>    | 45  | _    | _    | V          | $V_{GS} = 0V, I_D = 250\mu A$                |
| Zero Gate Voltage Drain Current            | I <sub>DSS</sub>     |     | _    | 100  | nA         | $V_{DS} = 45V, V_{GS} = 0V$                  |
| Gate-Source Leakage                        | I <sub>GSS</sub>     | _   | _    | ±100 | nA         | $V_{GS} = \pm 20V, V_{DS} = 0V$              |
| ON CHARACTERISTICS (Note 7)                |                      |     |      |      |            |  |
| Gate Threshold Voltage                     | V <sub>GS(th)</sub>  | 1   | _    | 3    | V          | $V_{DS} = V_{GS}$ , $I_D = 250 \mu A$        |
| Static Drain-Source On-Resistance          |                      |     | 37   | 46   | <b>~</b> 0 | $V_{GS} = 10V, I_D = 4.3A$                   |
| Static Dialii-Source Off-Resistance        | R <sub>DS (ON)</sub> |     | 52   | 62   | mΩ         | $V_{GS} = 4.5V, I_D = 4A$                    |
| Forward Transfer Admittance                | Y <sub>fs</sub>      |     | 4.5  | _    | S          | $V_{DS} = 10V, I_D = 4.3A$                   |
| Diode Forward Voltage                      | $V_{SD}$             |     | 0.7  | 1.2  | V          | $V_{GS} = 0V, I_{S} = 1A$                    |
| DYNAMIC CHARACTERISTICS (Note 8)           |                      |     |      |      |            |  |
| Input Capacitance                          | C <sub>iss</sub>     |     | 1287 | _    |            | V 05V V 0V                                   |
| Output Capacitance                         | Coss                 |     | 57   | _    | pF         | $V_{DS} = 25V, V_{GS} = 0V$<br>f = 1.0MHz    |
| Reverse Transfer Capacitance               | $C_{rss}$            |     | 44   | _    |            |  |
| Gate Resistance                            | $R_{G}$              |     | 1.2  | _    | Ω          | $V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$       |
| Total Gate Charge (V <sub>GS</sub> = 10V)  | $Q_g$                |     | 22.4 | _    |            |  |
| Total Gate Charge (V <sub>GS</sub> = 4.5V) | $Q_g$                |     | 10.4 | _    | nC         | V <sub>DS</sub> = 30V. I <sub>D</sub> = 4.3A |
| Gate-Source Charge                         | $Q_{gs}$             |     | 4.9  | _    | IIC        | $V_{DS} = 30V, I_{D} = 4.3A$                 |
| Gate-Drain Charge                          | $Q_{gd}$             |     | 3.0  | _    |            |  |
| Turn-On Delay Time                         | t <sub>D(on)</sub>   |     | 6.6  | _    |            |  |
| Turn-On Rise Time                          | t <sub>r</sub>       |     | 8.1  | _    | nS         | $V_{GS} = 10V, V_{DD} = 30V, R_G = 6\Omega,$ |
| Turn-Off Delay Time                        | t <sub>D(off)</sub>  | _   | 20.1 | _    | 113        | $I_D = 4.3A$                                 |
| Turn-Off Fall Time                         | t <sub>f</sub>       |     | 4.0  | _    |            |  |
| Body Diode Reverse Recovery Time           | t <sub>rr</sub>      | _   | 18   | _    | nS         | I <sub>S</sub> = 4.3A, dI/dt = 100A/µs       |
| Body Diode Reverse Recovery Charge         | Q <sub>rr</sub>      |     | 11.9 |      | nC         | I <sub>S</sub> = 4.3A, dI/dt = 100A/µs       |

Notes:

- 4. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
- 5. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
- 6.  $I_{AR}$  and  $E_{AR}$  rating are based on low frequency and duty cycles to keep  $T_J = 25^{\circ}$ C 7. Short duration pulse test used to minimize self-heating effect. 8. Guaranteed by design. Not subject to product testing.









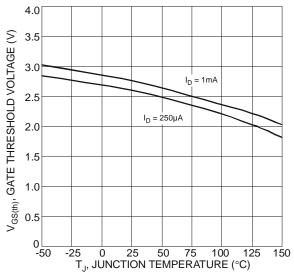


Fig. 10 Gate Threshold Variation vs. Ambient Temperature

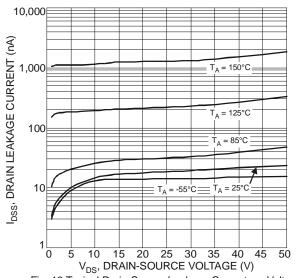
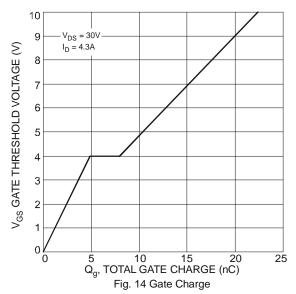
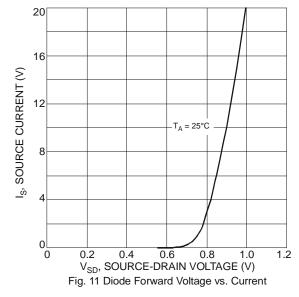
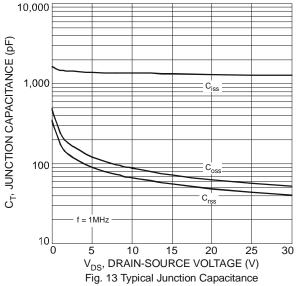


Fig. 12 Typical Drain-Source Leakage Current vs. Voltage

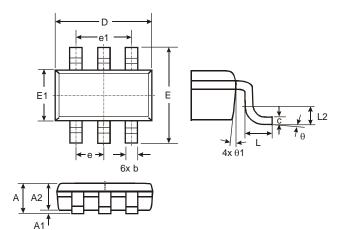






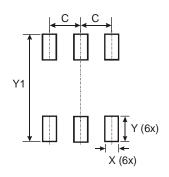


# **Package Outline Dimensions**



| TSOT26 |                      |           |      |  |  |  |  |
|--------|----------------------|-----------|------|--|--|--|--|
| Dim    | Min                  | Max       | Тур  |  |  |  |  |
| Α      | _                    | 1.00      | _    |  |  |  |  |
| A1     | 0.01                 | 0.10      | _    |  |  |  |  |
| A2     | 0.84                 | 0.90      | _    |  |  |  |  |
| D      | 1                    | 1         | 2.90 |  |  |  |  |
| Е      | 1                    | 1         | 2.80 |  |  |  |  |
| E1     | _                    | _         | 1.60 |  |  |  |  |
| b      | 0.30                 | 0.45      | _    |  |  |  |  |
| С      | 0.12                 | 0.20      | _    |  |  |  |  |
| е      | _                    | _         | 0.95 |  |  |  |  |
| e1     |                      |           | 1.90 |  |  |  |  |
| L      | 0.30                 | 0.30 0.50 |      |  |  |  |  |
| L2     |                      |           | 0.25 |  |  |  |  |
| θ      | 0°                   | 8°        | 4°   |  |  |  |  |
| θ1     | 4°                   | 12°       | _    |  |  |  |  |
| All D  | All Dimensions in mm |           |      |  |  |  |  |

# **Suggested Pad Layout**



| Dimensions | Value (in mm) |
|------------|---------------|
| С          | 0.950         |
| Х          | 0.700         |
| Y          | 1.000         |
| Y1         | 3.199         |



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